

- ☐ Tentative Specification  
☐ Preliminary Specification  
☒ Approval Specification

**MODEL NO.: G057VCE**  
**SUFFIX: TH1**

**Customer:**

**APPROVED BY**

**SIGNATURE**

**Name / Title**

Note

Please return 1 copy for your confirmation with your signature and comments.

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**REVISION HISTORY**

Version	Date	Page	Description
Ver 2.0	06, JAN, 2023	All	Approval Specification was first issued.

## 1. GENERAL DESCRIPTION

### 1.1 OVERVIEW

G057VCE-TH1 is a 5.7" TFT Liquid Crystal Display IAV module with LED Backlight units and 40 pins 1ch- TTL interface. This module supports 640 x 480 VGA mode and can display 262K colors.

The PSWG is to establish a set of displays with standard mechanical dimensions and select electrical interface requirements for an industry standard 5.7" VGA LCD panel and the LED driving device for Backlight is built in PCBA.

### 1.2 FEATURE

- VGA ( 640 x 480 pixels) resolution
- DE (Data Enable) mode and DE+SYNC mode selection
- TTL Interface
- PSWG (Panel Standardization Working Group)
- Wide operating temperature.
- Reversible scan direction
- RoHS compliance

### 1.3 APPLICATION

- TFT LCD Monitor
- Factory Application
- Amusement

### 1.4 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area	115.2 (H) x 86.4 (V) (5.7" diagonal)	mm	(1)
Driver Element	a-Si TFT active matrix	-	-
Pixel Number	640 x R.G.B x 480	pixel	-
Pixel Pitch	0.18(H) x 0.18(W)	mm	-
Pixel Arrangement	RGB vertical Stripe	-	-
Display Colors	262K	color	-
Display Mode	Normally Black	-	-
Surface Treatment	Hard Coating (3H), Anti-Glare	-	-
Module Power Consumption	2.818 ( Panel 0.518+BL 2.3)	W	Typ.

## 1.5 MECHANICAL SPECIFICATIONS

Item		Min.	Typ.	Max.	Unit	Note
Module Size	Horizontal(H)	143.5	144	144.5	mm	(1)
	Vertical(V)	104.1	104.6	105.1	mm	
	Depth(D)	11.8	12.3	12.8	mm	
Bezel Area	Horizontal	117.6	118.2	118.4	mm	-
	Vertical	88.8	89.4	89.6	mm	
Active Area	Horizontal	-	115.2	-	mm	
	Vertical	-	86.4	-	mm	
Weight		143	151	159	g	

Note (1) Please refer to the attached drawings for more information of front and back outline dimensions.

## 2. ABSOLUTE MAXIMUM RATINGS

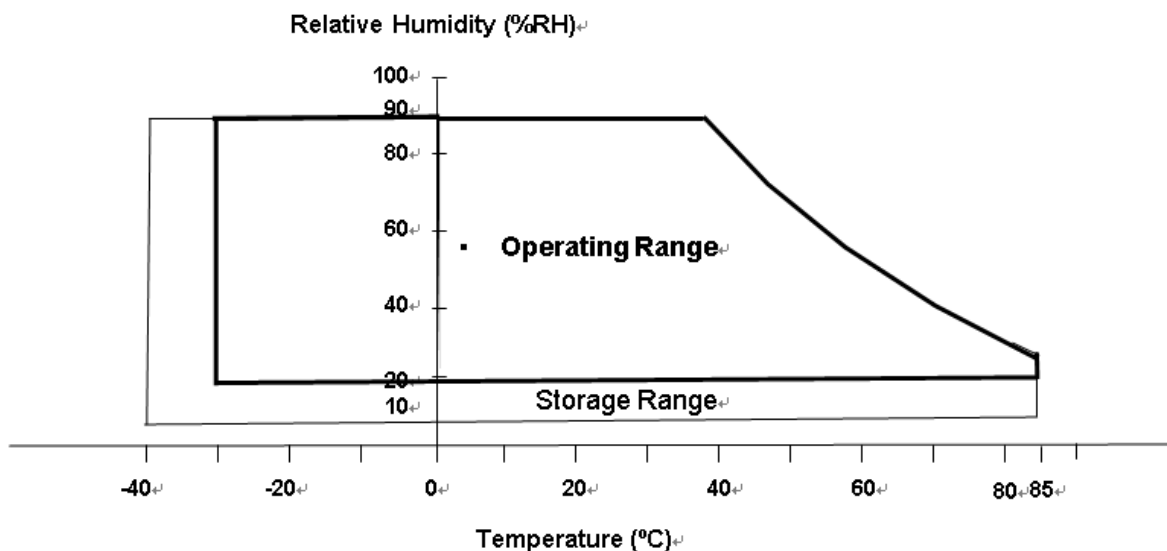
### 2.1 ABSOLUTE RATINGS OF ENVIRONMENT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Operating Ambient Temperature	T <sub>OP</sub>	-30	+85	°C	(1)(2)
Storage Temperature	T <sub>ST</sub>	-40	+85	°C	

Note (1)

- (a) 90 %RH Max.
- (b) Wet-bulb temperature should be 39 °C Max.
- (c) No condensation.

Note (2) Panel surface temperature should be 0°C min. and 85°C max under Vcc=5.0V, fr =60Hz, typical LED string current, 25°C ambient temperature, and no humidity control . Any condition of ambient operating temperature ,the surface of active area should be keeping not higher than 85°C .



## 2.2 ELECTRICAL ABSOLUTE RATINGS

### 2.2.1 TFT LCD MODULE

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Power Supply Voltage	VCC	-0.3	4	V	(1)
Logic Input Voltage	V <sub>IN</sub>	-0.3	4	V	

### 2.2.2 BACKLIGHT UNIT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Converter Voltage	V <sub>i</sub>	-0.3	18	V	(1) , (2)
Enable Voltage	EN	---	5.5	V	
Backlight Adjust	Dimming	---	5.5	V	

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for LED (Refer to 3.2 for further information).



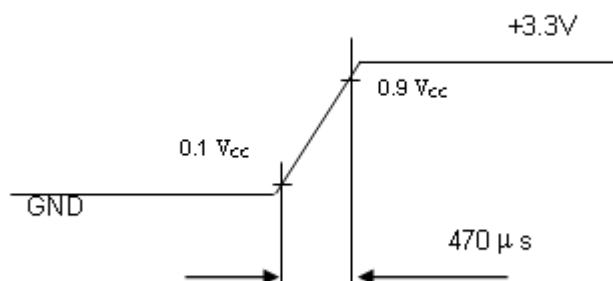
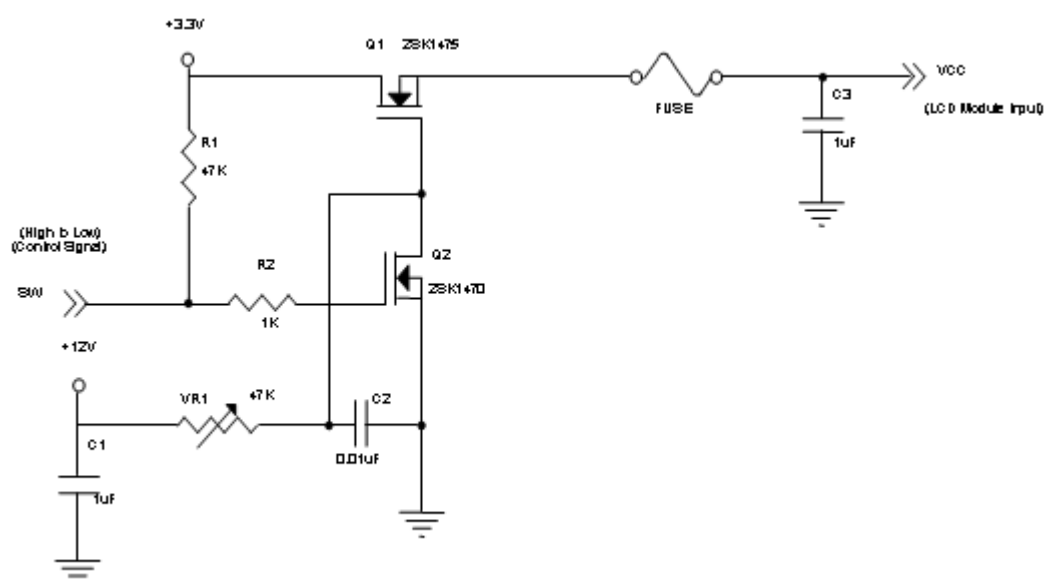
### 3. ELECTRICAL CHARACTERISTICS

### 3.1 TFT LCD MODULE

Parameter		Symbol	Value			Unit	Note
			Min.	Typ.	Max.		
Power Supply Voltage		$V_{CC}$	3.0	3.3	3.6	V	-
Ripple Voltage		$V_{RP}$	-	-	100	mVp-p	
Inrush Current		$I_{INRUSH}$	-	-	2.0	A	(2)
Power Supply Current	White	$I_{CC}$	-	157	187	mA	(3)a
	Black		-	106	125	mA	(3)b
Power Consumption		$P_L$	-	0.518	0.617	W	
Logic High Input Voltage		$V_{IH}$	$0.7V_{CC}$		$V_{CC}$	V	
Logic Low Input Voltage		$V_{IL}$	GND		$0.3V_{CC}$	V	

Note (1) The module should be always operated within above ranges.

Note (2) Measurement Conditions:



Note (3) The specified power supply current is under the conditions at  $V_{DD} = 3.3V$ ,  $T_a = 25 \pm 2^\circ C$ , DC Current and  $f_v = 60$  Hz, whereas a power dissipation check pattern below is displayed.

a. White Pattern



Active Area

b. Black Pattern

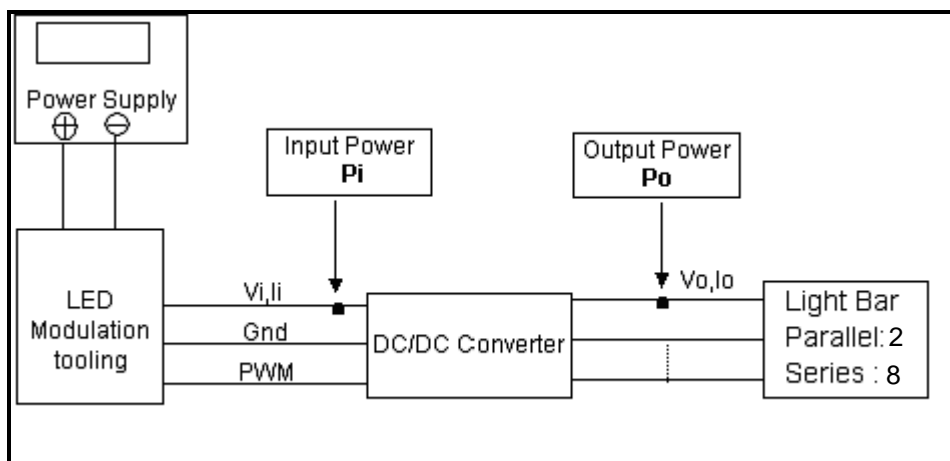


Active Area

## 3.2 BACKLIGHT UNIT

Parameter		Symbol	Value			Unit	Note
			Min.	Typ.	Max.		
Converter Input Voltage		$V_i$	10.8	12.0	13.2	$V_{DC}$	(Duty 100%)
Converter Input Ripple Voltage		$V_{iRP}$	-	-	500	mV	
Converter Input Current		$I_i$	0.16	0.19	0.22	$A_{DC}$	@ $V_i = 12V$ (Duty 100%)
Converter Inrush Current		$I_{rush}$	-	-	3.0	A	@ $V_i$ rising time=10ms ( $V_i=12V$ )
Input Power Consumption		$P_i$	-	2.3		W	(1)
EN Control Level	Backlight on	ENLED (BLON)	2.0	3.3	5.0	V	
	Backlight off		0	-	0.3	V	
PWM Control Level	PWM High Level	Dimming (E_PWM)	2.0	-	5.0	V	
	PWM Low Level		0	-	0.15	V	
PWN Noise Range		$V_{Noise}$	-	-	0.1	V	
PWM Control Frequency		$f_{PWM}$	190	200	20k	Hz	(2)
PWM Dimming Control Duty Ratio		-	5	-	100	%	(2), @ $190Hz < f_{PWM} < 1kHz$
			20	-	100	%	(2), @ $1kHz \leq f_{PWM} < 20kHz$
LED Life Time		$L_{LED}$	50,000		-	Hrs	(3)

Note (1) LED current is measured by utilizing a high frequency current meter as shown below:

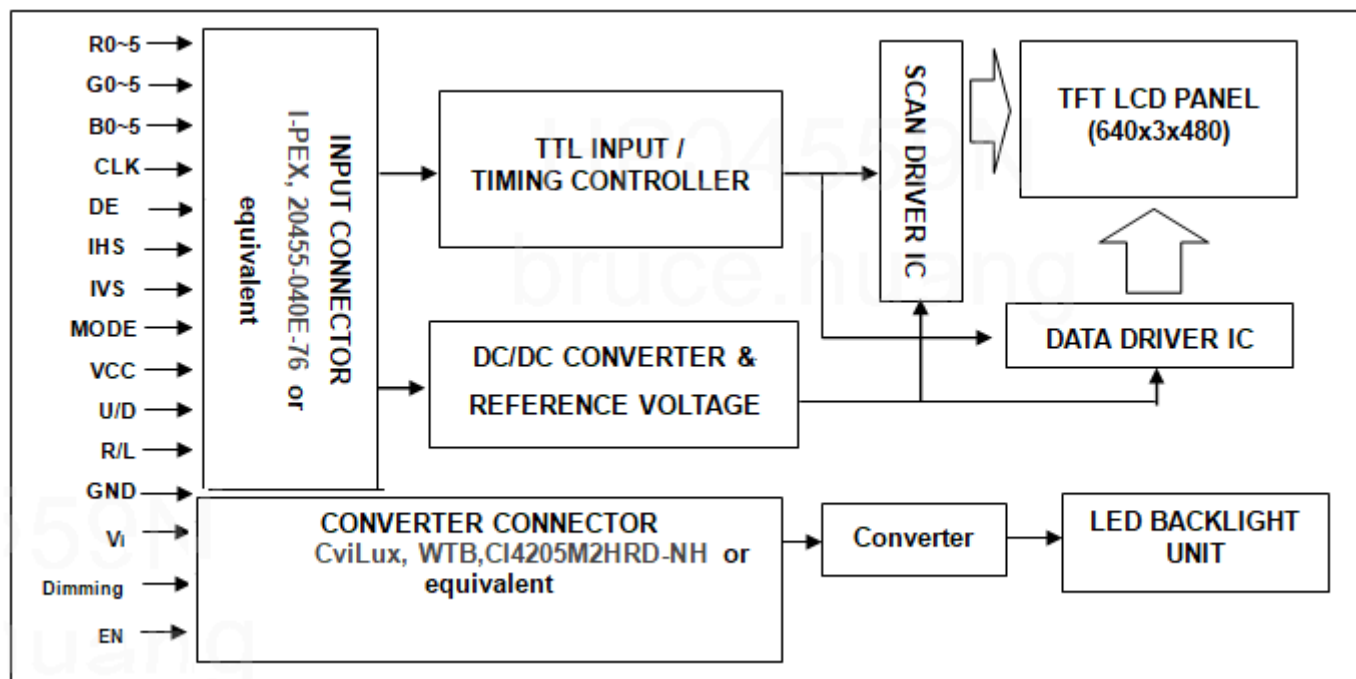


Note (2) The lifetime of LED is estimated data and defined as the time when it continues to operate under the conditions at  $T_a = 25 \pm 2^\circ C$  and Duty 100% until the brightness becomes  $\leq 50\%$  of its original value. Operating LED at high temperature condition will reduce life time and lead to color shift.

Note (3) At 190 ~1kHz PWM control frequency, duty ratio range is restricted from 5% to 100%. 1K ~20kHz PWM control frequency, duty ratio range is restricted from 20% to 100%. If PWM control frequency is applied in the range from 1KHz to 20KHz, The “non-linear” phenomenon on the Backlight Unit may be found. So It’ s a **suggestion** that PWM control frequency should be **less than 1KHz**.

## 4. BLOCK DIAGRAM

### 4.1 TFT LCD MODULE



## 5. INPUT TERMINAL PIN ASSIGNMENT

### 5.1 TFT LCD MODULE

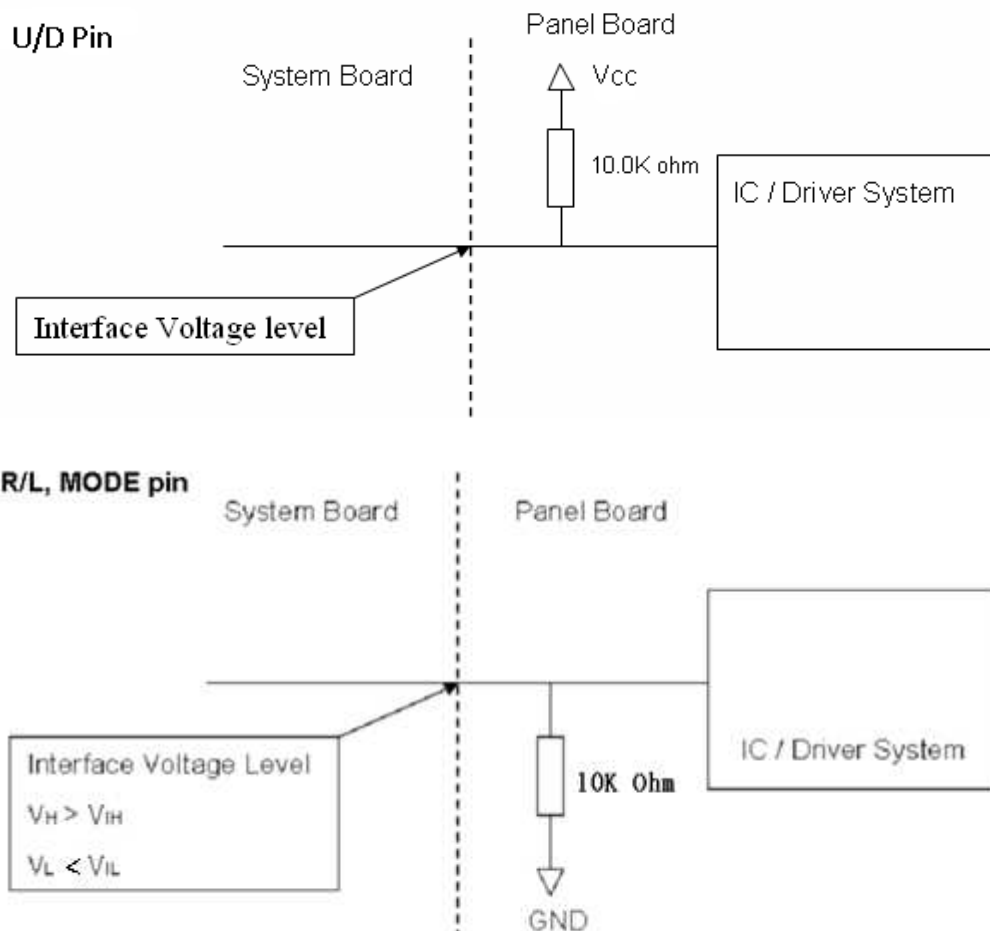
Pin No.	Symbol	Function	Note
1	GND	Ground	
2	CLK	Dot Clock. Latch data at the rising edge.	
3	IHS	Horizontal synchronous signal	
4	IVS	Vertical synchronous signal	
5	GND	Ground	
6	R5	Red data (MSB)	
7	R4	Red data	
8	R3	Red data	
9	R2	Red data	
10	R1	Red data	
11	R0	Red data (LSB)	
12	GND	Ground	
13	G5	Green data (MSB)	
14	G4	Green data	
15	G3	Green data	
16	G2	Green data	
17	G1	Green data	
18	G0	Green data (LSB)	
19	GND	Ground	
20	B5	Blue data (MSB)	Note (3)
21	B4	Blue data	
22	B3	Blue data	
23	B2	Blue data	
24	B1	Blue data	
25	B0	Blue data (LSB)	
26	GND	Ground	
27	DE	Data Enable Signal	
28	NC	No Connection	Note (3)
29	NC	No Connection	Note (3)
30	R/L	Horizontal Reverse Scan Control, Low or NC → Normal Mode. High → Horizontal Reverse Scan	Note (3)
31	U/D	Vertical Reverse Scan Control, High or NC → Normal Mode Low → Vertical Reverse Scan	Note (3)
32	NC	No Connection	Note (3) Note (4)
33	NC	No Connection	Note (3) Note (4)
34	NC	No Connection	Note (3) Note (4)
35	MODE	DE / HV mode select. High → HV mode. Low or NC → DE mode.	Note (3)
36	NC	No Connection	Note (3) Note (4)
37	NC	No Connection	Note (3)
38	VCC	Power supply: +3.3V	
39	VCC	Power supply: +3.3V	
40	VCC	Power supply: +3.3V	

Note (1) Connector Part No.: 20455-040E-76(I-PEX) or equivalent.

Note (2) User's connector Part No.: 20453-040T-03(I-PEX) or equivalent.

Note (3) "Low" stands for 0V. "High" stands for 3.3V. "NC" stands for "No Connection".

Note (4) Pin32, Pin33, Pin34, Pin36 input signals should be set to no connection or ground, this module would operate normally.

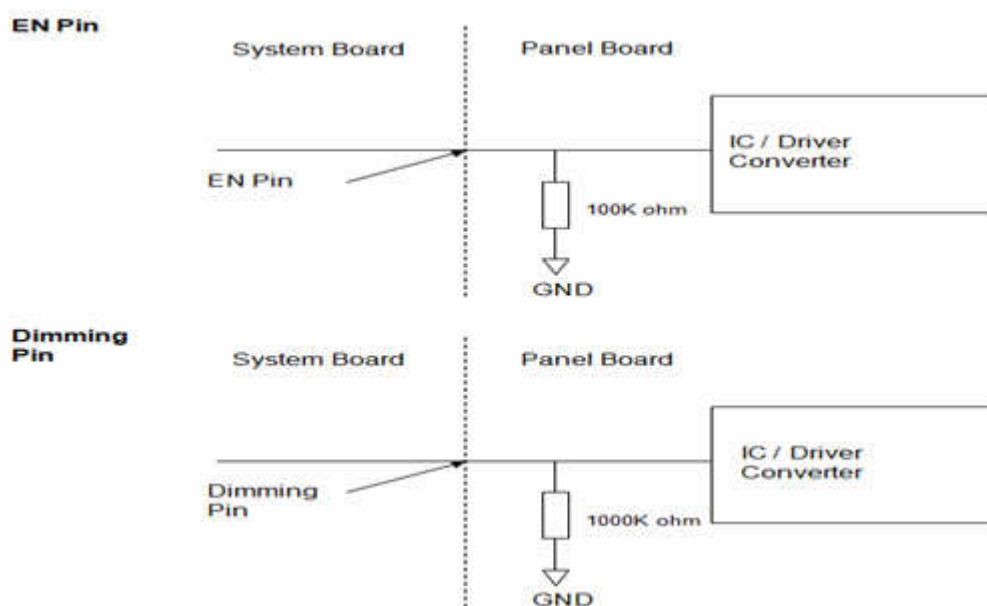


## 5.2 BACKLIGHT UNIT(CONVERTER CONNECTOR PIN)

Pin	Symbol	Description	Remark
1	NC	Not Connect	
2	Dimming	Backlight Adjust	PWM Dimming (Hi: 3.3V <sub>DC</sub> , Lo: 0V <sub>DC</sub> )
3	EN	Enable pin	3.3V
4	V <sub>GND</sub>	Converter ground	Ground
5	V <sub>i</sub>	Converter input voltage	12V

Note (1)Connector Part No.: CI4205M2HRD-NH (Cvilux) or equivalent.

Note (2)User's connector Part No.: 9827H-04-N0HF(SWB) or equivalent.



## 5.3 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 6-bit gray scale data input for the color. The higher the binary input the brighter the color. The table below provides the assignment of color versus data input.

Color		Data Signal																	
		Red						Green						Blue					
		R5	R4	R3	R2	R1	R0	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1	B0
Basic Colors	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	1	1	1	1	1	1	0	0	0	0	0	0
	Blue	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1
	Cyan	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	0	0	0	0	0	0	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Gray Scale Of Red	Red(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(1)	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0
	Red(2)	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0
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	Red(61)	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0
	Red(62)	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0
Red(63)	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	
Gray Scale Of Green	Green(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0
	Green(2)	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0
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	Green(61)	0	0	0	0	0	0	1	1	1	1	0	1	0	0	0	0	0	0
	Green(62)	0	0	0	0	0	0	1	1	1	1	1	0	0	0	0	0	0	0
Green(63)	0	0	0	0	0	0	1	1	1	1	1	1	0	0	0	0	0	0	
Gray Scale Of Blue	Blue(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
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	Blue(61)	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	0	1
	Blue(62)	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	0
Blue(63)	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	

Note (1)0: Low Level Voltage, 1: High Level Voltage



## 6. INTERFACE TIMING

### 6.1 INPUT SIGNAL TIMING SPECIFICATIONS

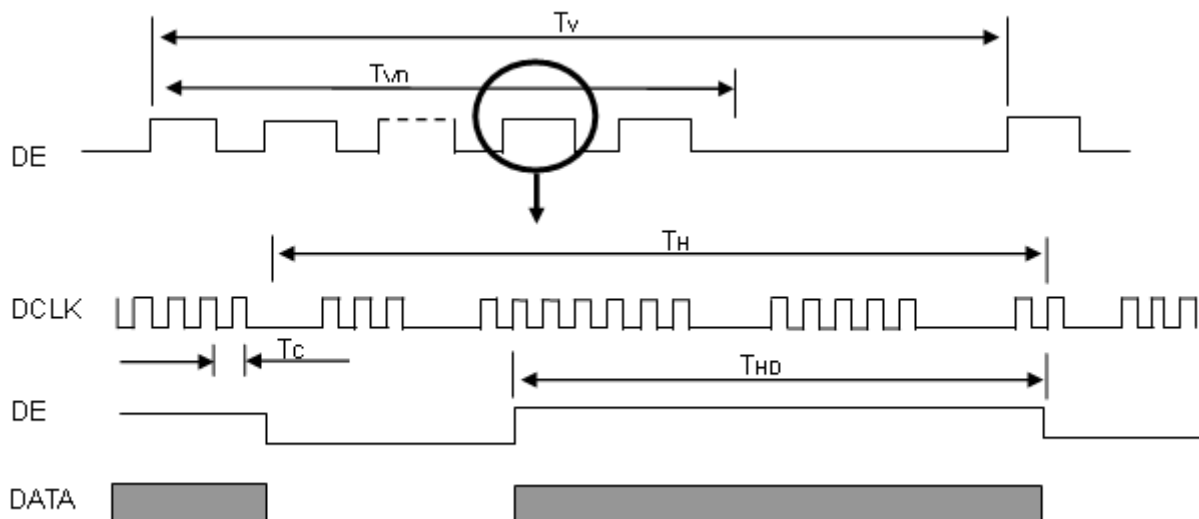
The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Typ.	Max.	Unit	Note
DCLK	Frequency	$F_r$	23.9	25.2	29.8	MHz	-
	Period	$T_c$	33.56	39.71	41.84	ns	
	Input cycle to cycle jitter	$T_{rdl}$	---	---	200	ns	(a)
	Spread spectrum modulation range	$F_{clkin\_mod}$	$0.98 \cdot F_c$	-	$1.02 \cdot F_c$	MHz	(b)
	Spread spectrum modulation frequency	$F_{SSM}$	-	-	200	KHz	
Vertical Display Term	Frame Rate	$F_r$	---	60	---	Hz	$T_v = T_{vd} + T_{vb}$
	Total	$T_v$	515	525	611	$T_h$	-
	Active Display	$T_{vd}$	480	480	480	$T_h$	-
	Blank	$T_{vb}$	35	45	131	$T_h$	-
Horizontal Display Term	Total	$T_h$	750	800	814	$T_c$	$T_h = T_{hd} + T_{hb}$
	Active Display	$T_{hd}$	640	640	640	$T_c$	-
	Blank	$T_{hb}$	110	160	174	$T_c$	-

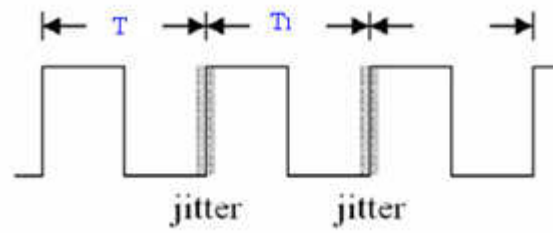
Note (1) Because this module is operated by DE only mode, Hsync and Vsync input signals should be set to low logic level or ground. Otherwise, this module would operate abnormally.

Note (2) The  $T_v(T_{vd}+T_{vb})$  must be integer, otherwise, the module would operate abnormally.

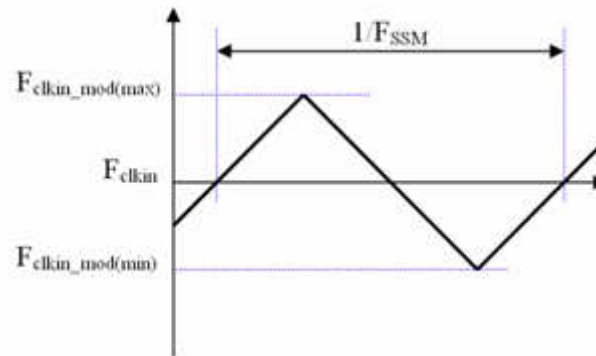
#### INPUT SIGNAL TIMING DIAGRAM



Note (a) The input clock cycle-to-cycle jitter is defined as below figures.  $T_{rc1} = |T_1 - T_1|$



Note (b) The SSCG (Spread spectrum clock generator) is defined as below figures.



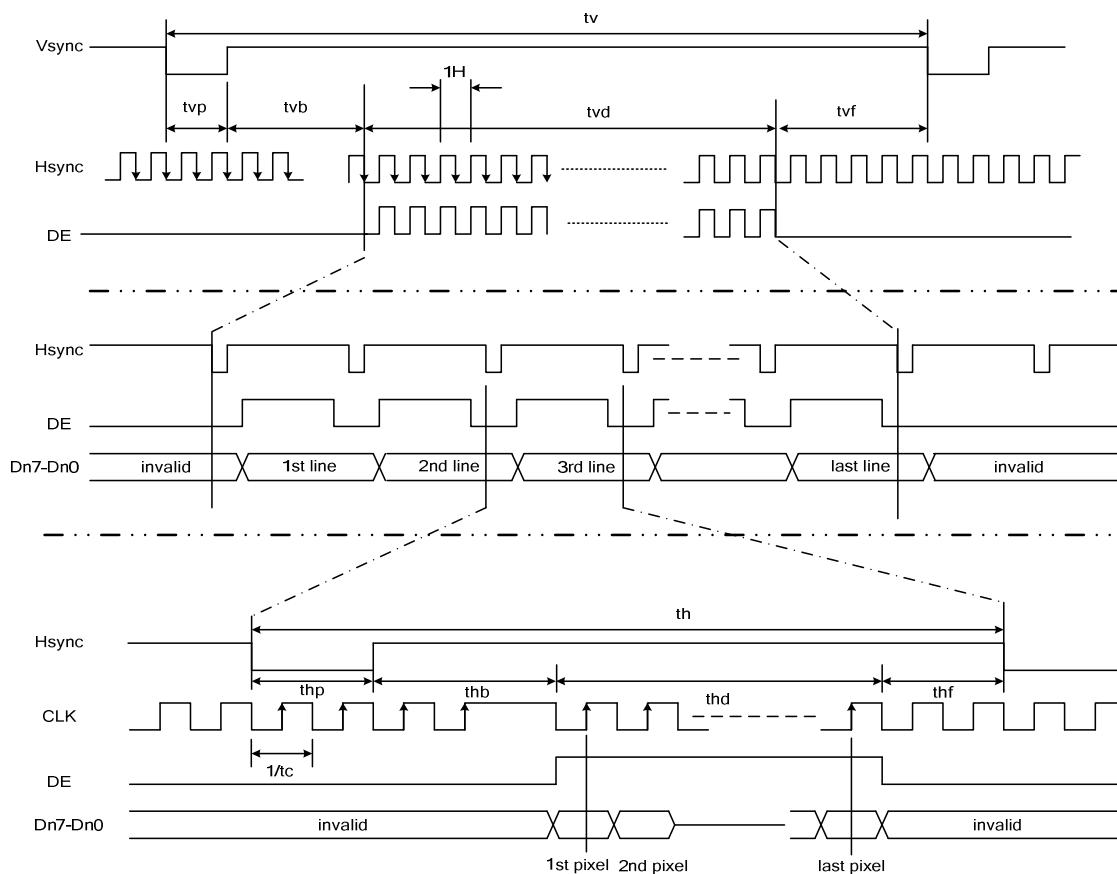
## 6.2 DE +Sync Mode INPUT SIGNAL TIMING SPECIFICATIONS

The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Typ.	Max.	Unit	Note
DCLK	Frequency	Tc	23.9	25.2	29.8	MHz	
Vertical Active Display Term	Total	Tv	515	525	611	Th	
	Display	Tvd	-	480	-	Th	
	Front Porch	Tvf	3	10	126	Th	
	Back Porch	Tvb	-	33	-	Th	
	VS Pluse width	Tvp	1	2	4	Th	
Horizontal Active Display Term	Total	Th	750	800	814	Tc	
	Display	Thd	-	640	-	Tc	
	Front Porch	Thf	28	126	142	Tc	
	Back Porch	Thb	-	32	-	Tc	
	HS Pluse width	Thp	1	2	31	Tc	

Note (1) The Tv(Tvd+Tvb+Tvf+Tvp) must be integer, otherwise, the module would operate abnormally

### INPUT SIGNAL TIMING DIAGRAM

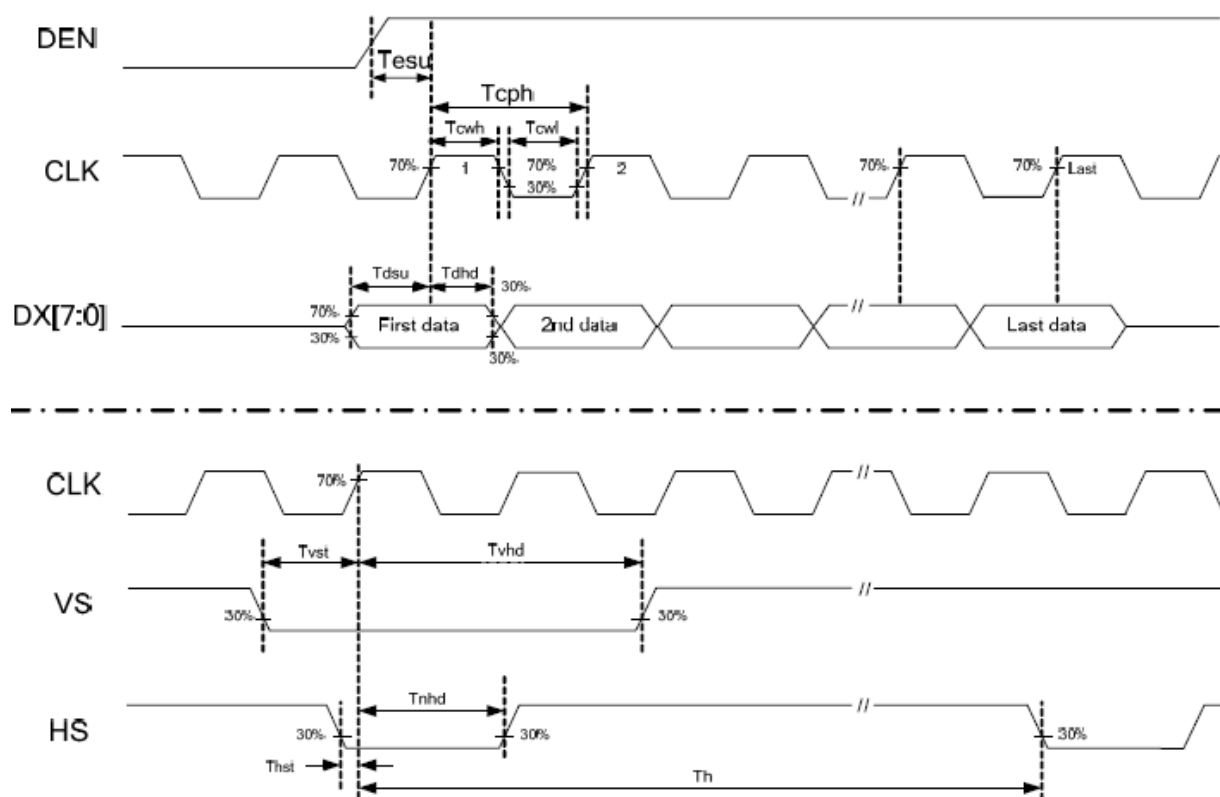


## 6.3 AC ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Value			Unit	Condition
		Min.	Typ.	Max.		
Data setup time	Tdsu	10	-	-	ns	Note (1)
Data hold time	Tdhd	10	-	-	ns	Note (1)
DE setup time	Tesu	10	-	-	ns	
HS setup time	Thst	10	-	-	ns	
HS hold time	Thhd	10	-	-	ns	
VS setup time	Tvst	10	-	-	ns	
VS hold time	Tvhd	10	-	-	ns	

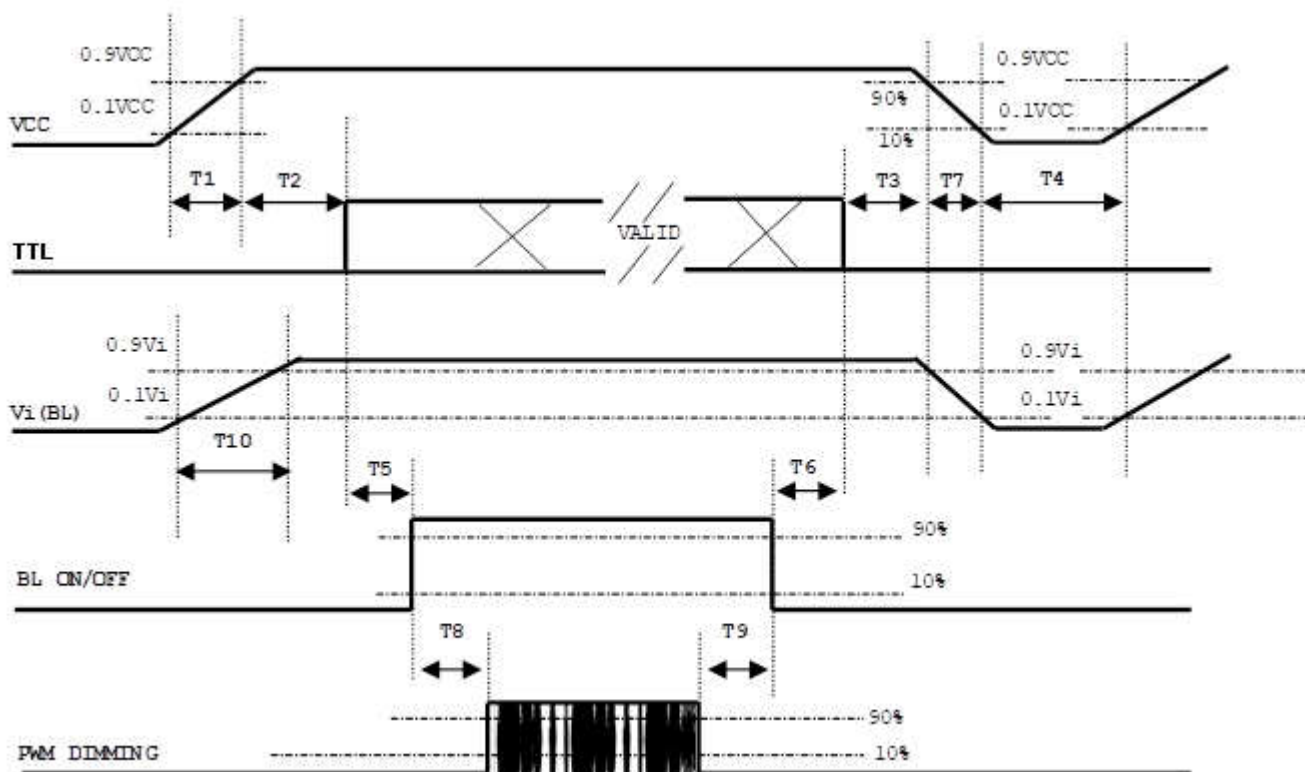
Note (1) CLK latching data at the rising edge.

**Clock and Data input waveform**



## 6.4 POWER ON/OFF SEQUENCE

To prevent a latch-up or DC operation of LCD assembly, the power on/off sequence should be as the diagram below.



Parameter	Value			Units
	Min	Typ	Max	
T1	0.5	-	10	ms
T2	0	-	50	ms
T3	0	-	50	ms
T4	500	-	-	ms
T5	450	-	-	ms
T6	200	-	-	ms
T7	10	-	100	ms
T8	10	-	-	ms
T9	10	-	-	ms
T10	20	-	50	ms

Note(1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.

Note(2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.

Note(3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.

Note(4) T4 should be measured after the module has been fully discharged between power off and on period.

Note(5) Interface signal shall not be kept at high impedance when the power is on.

Note(6) INX won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.

Note(7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "T7 spec

## 6.5 SCANNING DIRECTION

The following figures show the image see from the front view. The arrow indicates the direction of scan.

Fig.1 Normal Scan



Fig.2 Reverse Scan



Fig.3 Reverse Scan



Fig.4 Reverse Scan



PCBA on the top side

PCBA on the top side

Fig. 1 Normal scan ( pin 30,R/L=Low or NC, pin 31,U/D = High or NC)

Fig. 2 Reverse scan (pin 30,R/L=High, pin 31,U/D = High or NC )

Fig. 3 Reverse scan (pin 30,R/L=Low or NC, pin 31,U/D = Low )

Fig. 4 Reverse scan (pin 30,R/L=High, pin 31,U/D = Low )

## 7. OPTICAL CHARACTERISTICS

### 7.1 TEST CONDITIONS

Item	Symbol	Value	Unit
Ambient Temperature	Ta	25±2	oC
Ambient Humidity	Ha	50±10	%RH
Supply Voltage	According to typical value and tolerance in "ELECTRICAL CHARACTERISTICS"		
Input Signal			
PWM Duty Ratio	D	100	%

### 7.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown here and all items are measured at the center point of screen unless otherwise noted. The following items should be measured under the test conditions described above and stable conditions shown in Note (5).

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Color Chromaticity	Red	Rx	$\theta X=0^{\circ}, \theta Y=0^{\circ}$ Grayscale Maximum	0.597	0.647	0.697	-	(1), (5)
		Ry		0.290	0.340	0.390		
	Green	Gx		0.270	0.320	0.370		
		Gy		0.553	0.603	0.653		
	Blue	Bx		0.102	0.152	0.202		
		By		0.000	0.050	0.100		
	White	Wx		0.263	0.313	0.363		
		Wy		0.279	0.329	0.379		
Center Luminance of White		LC	360	450			(4), (5)	
Contrast Ratio		CR	700	1000			(2), (5)	
Response Time		TR	$\theta X=0^{\circ}, \theta Y=0^{\circ}$	-	13	18	-	(3)
		TF		-	12	17	-	
White Variation		$\delta W$	$\theta X=0^{\circ}, \theta Y=0^{\circ}$	72	80	-	%	(5), (6)
Viewing Angle	Horizontal	$\theta X+$	$CR \geq 10$	80	89	-	Deg.	(1), (5)
		$\theta X-$		80	89	-		
	Vertical	$\theta Y+$		80	89	-		
		$\theta Y-$		80	89	-		

Definition :

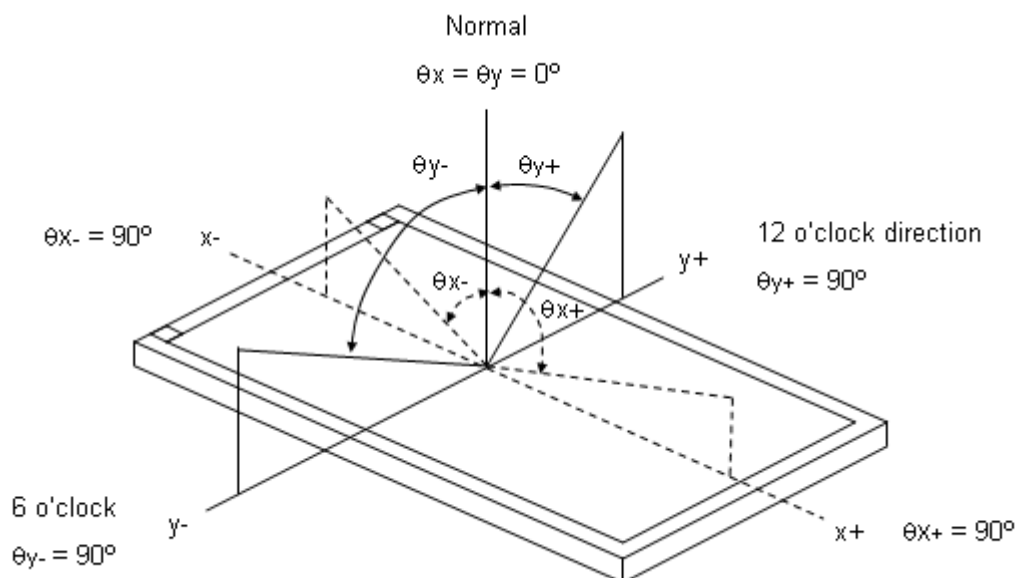
Grayscale Maximum : Grayscale 255 (10 bits: grayscale 1023 ; 8 bits : grayscale 255 ; 6 bits: grayscale 63)

White : Luminance of Grayscale Maximum (All R,G,B)

Black : Luminance of grayscale 0 (All R,G,B)



Note (1) Definition of Viewing Angle ( $\theta_x$ ,  $\theta_y$ ):

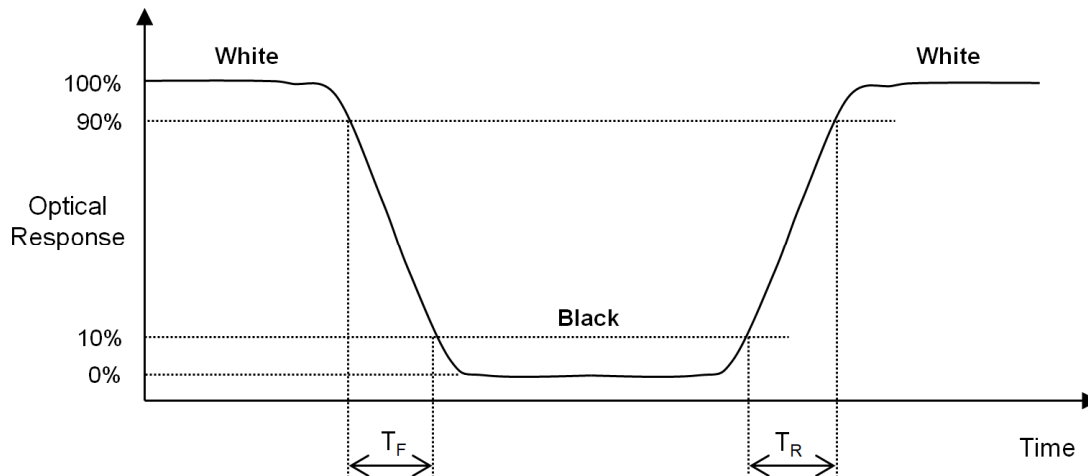


Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression at center point.

$$\text{Contrast Ratio (CR)} = \text{White} / \text{Black}$$

Note (3) Definition of Response Time ( $T_R$ ,  $T_F$ ):

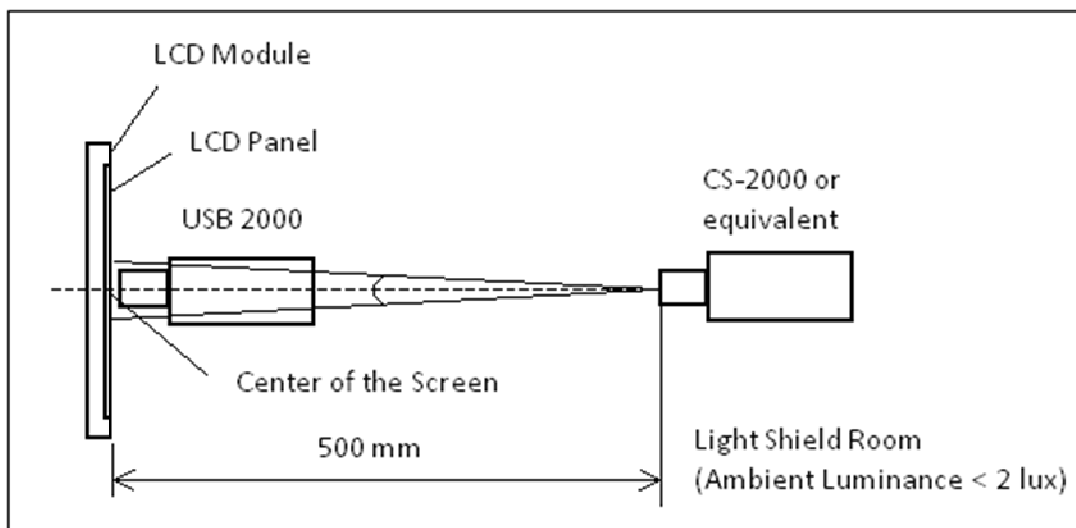


Note (4) Definition of Luminance of White ( $L_c$ ):

Measure the luminance of White at center point.

Note (5) Measurement Setup:

The LCD module should be stabilized at given temperature to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 40 minutes in a windless room. The measurement placement of module should be in accordance with module drawing.

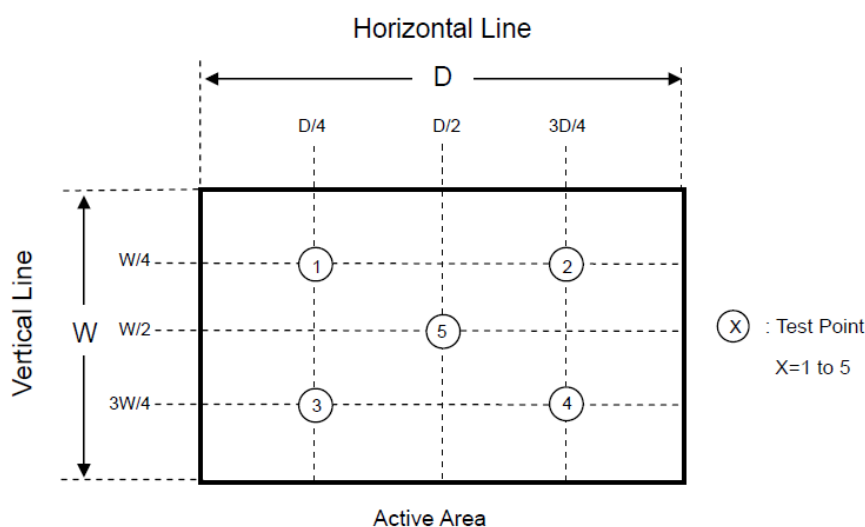


Note (6) Definition of White Variation ( $\delta W$ ):

Measure the luminance of White at 5 points.

Luminance of White :  $L(X)$  , where X is from 1 to 5.

$$\delta W = \frac{\text{Minimum [ } L(1) \text{ to } L(5) \text{]}}{\text{Maximum [ } L(1) \text{ to } L(5) \text{]}} \times 100\%$$



## 8. RELIABILITY TEST CRITERIA

Test Item	Test Condition	Note
High Temperature Storage Test	85°C, 240 hours	(1), (2) (4), (5)
Low Temperature Storage Test	-40°C, 240 hours	
Thermal Shock Storage Test	-30°C, 0.5 hour $\longleftrightarrow$ 70°C, 0.5 hour; 100cycles, 1 hour/cycle)	
High Temperature Operation Test	85°C, 240 hours	
Low Temperature Operation Test	-30°C, 240 hours	
High Temperature & High Humidity Operation Test	60°C, RH 90%, 240 hours	(1), (4)
ESD Test (Operation)	150pF, 330Ω, 1 sec/cycle Condition 1 : panel contact, $\pm 8$ KV Condition 2 : panel non-contact $\pm 15$ KV	
Shock (Non-Operating)	50G, 11ms, half sine wave, 1 time for $\pm X$ , $\pm Y$ , $\pm Z$ direction	
Vibration (Non-Operating)	1.5G, 10 ~ 300 Hz sine wave, 10 min/cycle, 3 cycles each X, Y, Z direction	(2), (3)

Note (1) There should be no condensation on the surface of panel during test ,

Note (2) Temperature of panel display surface area should be 85°C Max.

Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.

Note (4) In the standard conditions, there is no function failure issue occurred. All the cosmetic specification is judged before reliability test.

Note (5) Before cosmetic and function test, the product must have enough recovery time, at least 24 hours at room temperature.

## 9. PACKAGING

### 9.1 PACKING SPECIFICATIONS

- (1) 60pcs LCD modules / 1 Box
- (2) Box dimensions: 500 (L) X 400 (W) X 330 (H) mm
- (3) Weight: approximately 11.65Kg (60 modules per box)

### 9.2 PACKING METHOD

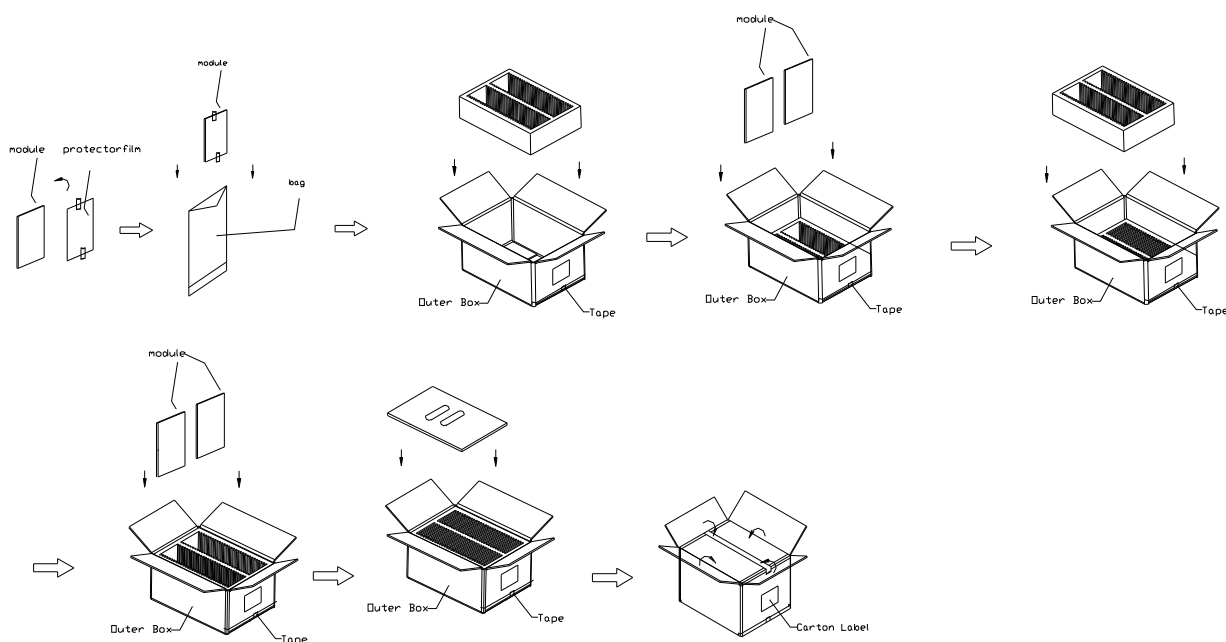


Figure. 9-1 Packing

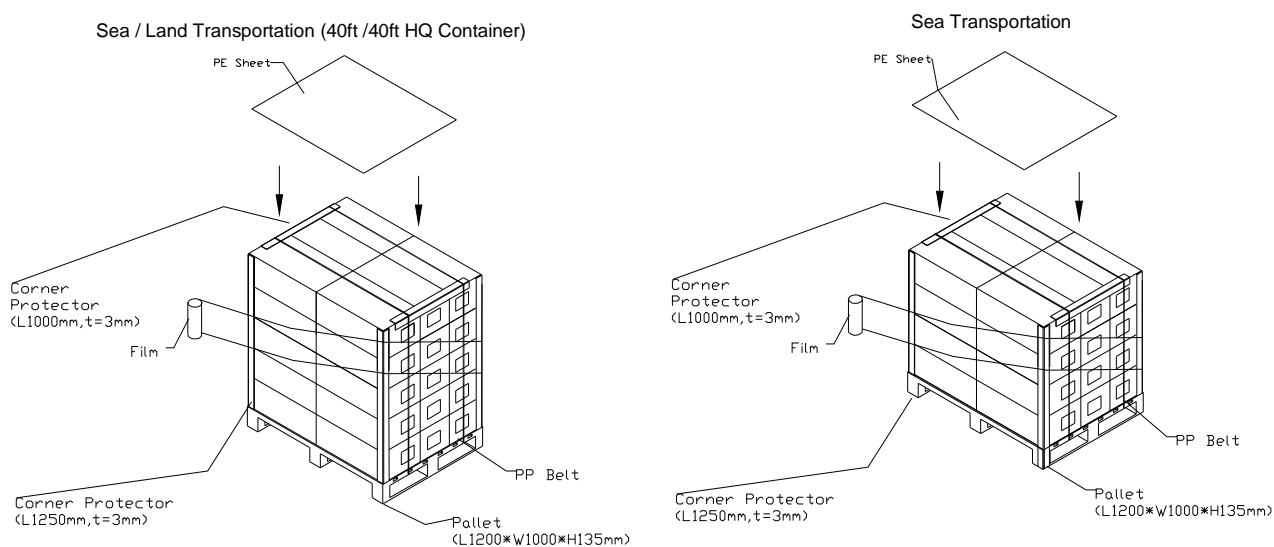


Figure. 9-2 Packing

### 9.3 UN-PACKING METHOD

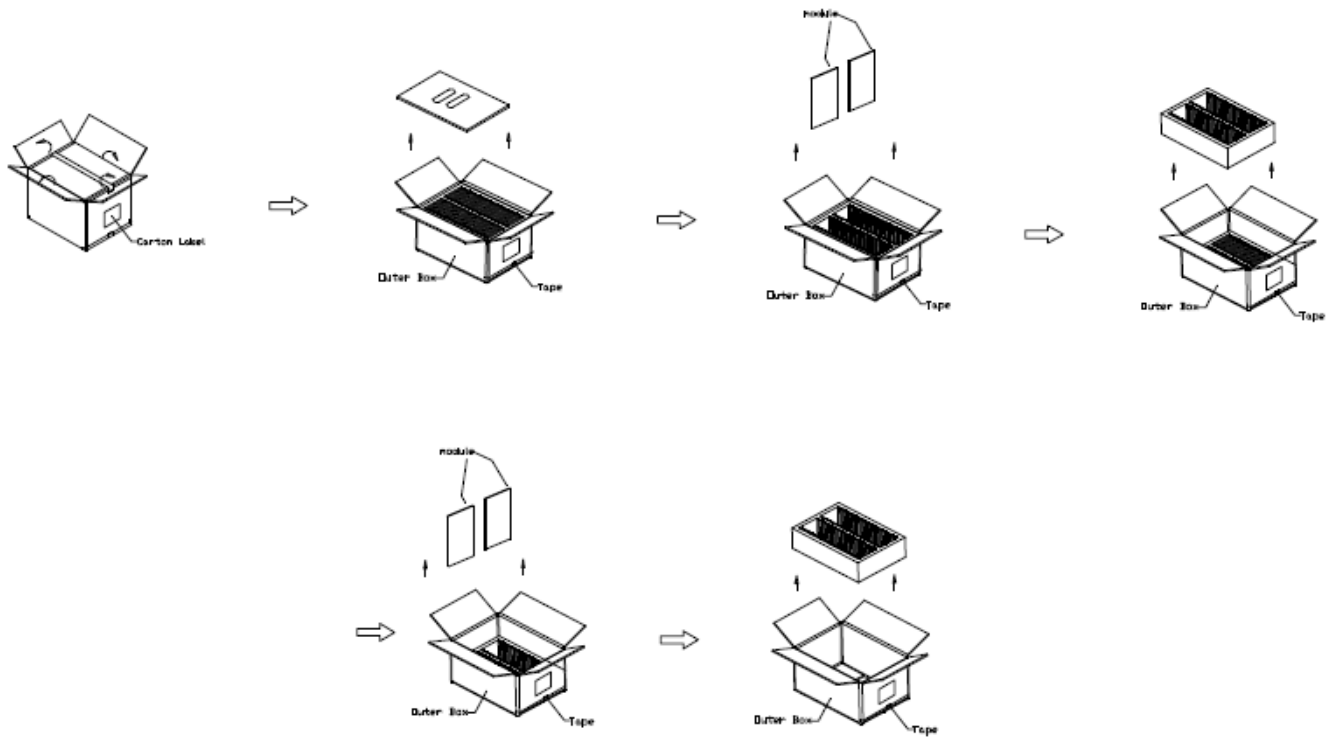


Figure. 9-3 Un-packing method

## 10. DEFINITION OF LABELS

### 10.1 INX MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.

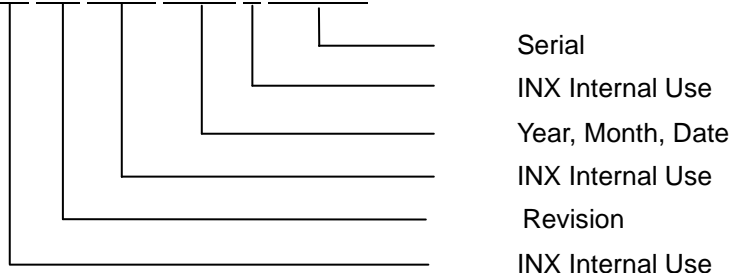


Note (1) Safety Compliance(UL logo) will open after C1 version.

(a) Model Name: G057VCE-TH1

(b) \* \* \* \* : Factory ID

(c) Serial ID: XXXXXXYMDXNNNN



Serial ID includes the information as below:

(a) Manufactured Date: Year: 1~9, for 2021~2029

Month: 1~9, A~C, for Jan. ~ Dec.

Day: 1~9, A~Y, for 1<sup>st</sup> to 31<sup>st</sup>, exclude I , O and U

(b) Revision Code: cover all the change

(c) Serial No.: Manufacturing sequence of product

## **11. PRECAUTIONS**

### **11.1 ASSEMBLY AND HANDLING PRECAUTIONS**

- (1)The module should be assembled into the system firmly by using every mounting hole. Be careful not to twist or bend the module.
- (2)While assembling or installing modules, it can only be in the clean area. The dust and oil may cause electrical short or damage the polarizer.
- (3)Use fingerstalls or soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (4)Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.
- (5)If the surface of the polarizer is dirty, please clean it by some absorbent cotton or soft cloth. Do not use Ketone type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanently damage the polarizer due to chemical reaction.
- (6)Wipe off water droplets or oil immediately. Staining and discoloration may occur if they left on panel for a long time.
- (7)If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contacting with hands, legs or clothes, it must be washed away thoroughly with soap.
- (8)Protect the module from static electricity, it may cause damage to the C-MOS Gate Array IC.
- (9)Do not disassemble the module.
- (10)Do not pull or fold the lamp wire.
- (11)Pins of I/F connector should not be touched directly with bare hands.

### **11.2 STORAGE PRECAUTIONS**

- (1)When storing for a long time, the following precautions are necessary.
  - (a)Store them in a dark place. Do not expose the module to sunlight or fluorescent light. Keep the temperature between 5°C and 30°C at humidity 50+-10%RH.
  - (b) The polarizer surface should not come in contact with any other object.
  - (c) It is recommended that they be stored in the container in which they were shipped.
  - (d) Storage condition is guaranteed under packing conditions.
  - (e)The phase transition of Liquid Crystal in the condition of the low or high storage temperature will be recovered when the LCD module returns to the normal condition
- (2)High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (3)It is dangerous that moisture come into or contacted the LCD module, because the moisture may damage LCD module when it is operating.
- (4)It may reduce the display quality if the ambient temperature is lower than 10 °C. For example, the response time will become slowly, and the starting voltage of lamp will be higher than the room temperature.

## 11.3 OTHER PRECAUTIONS

(1) Normal operating condition

(a) Display pattern: dynamic pattern (Real display)

(Note) Long-term static display can cause image sticking.

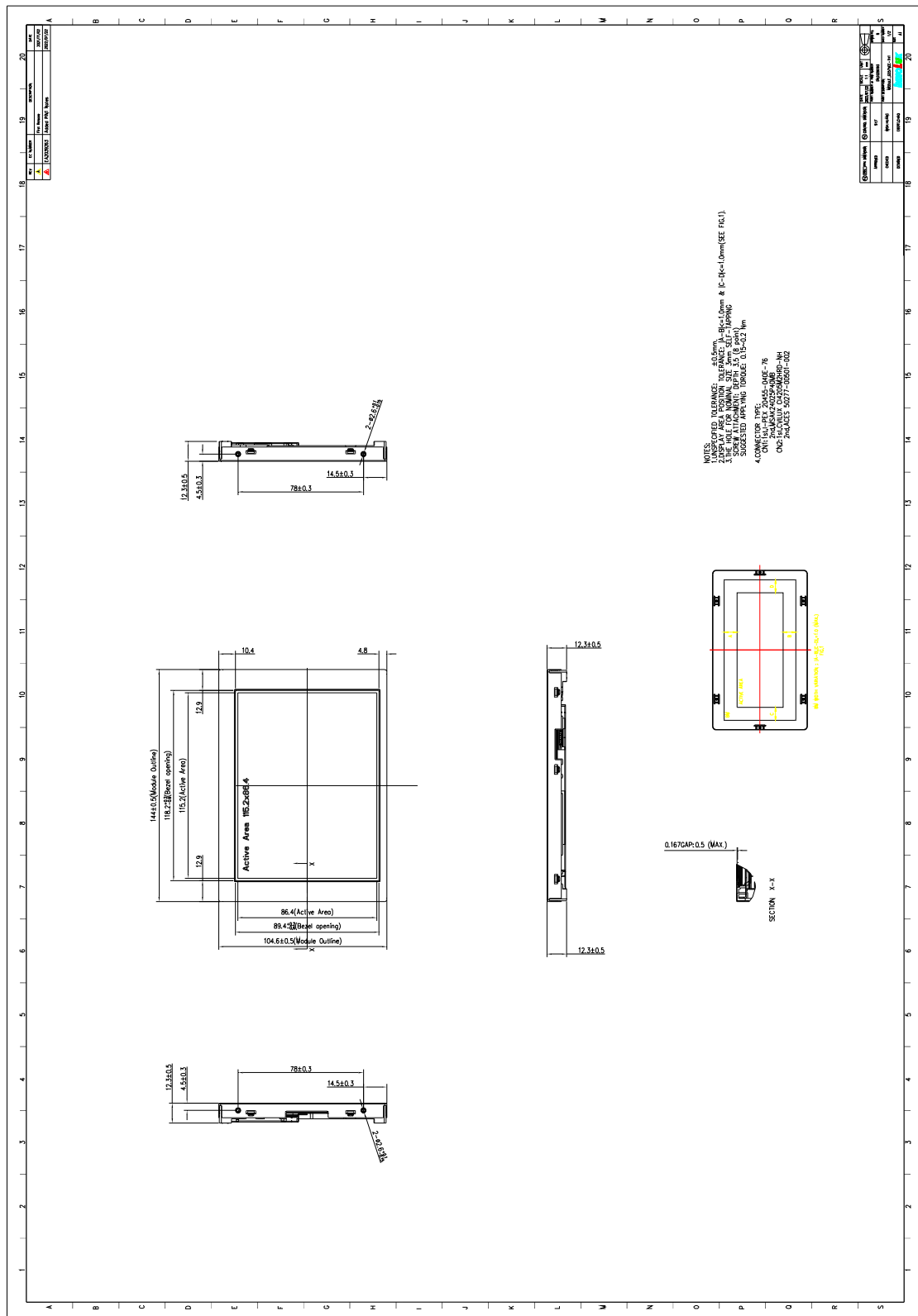
(2) Operating usages to protect against image sticking due to long-term static display

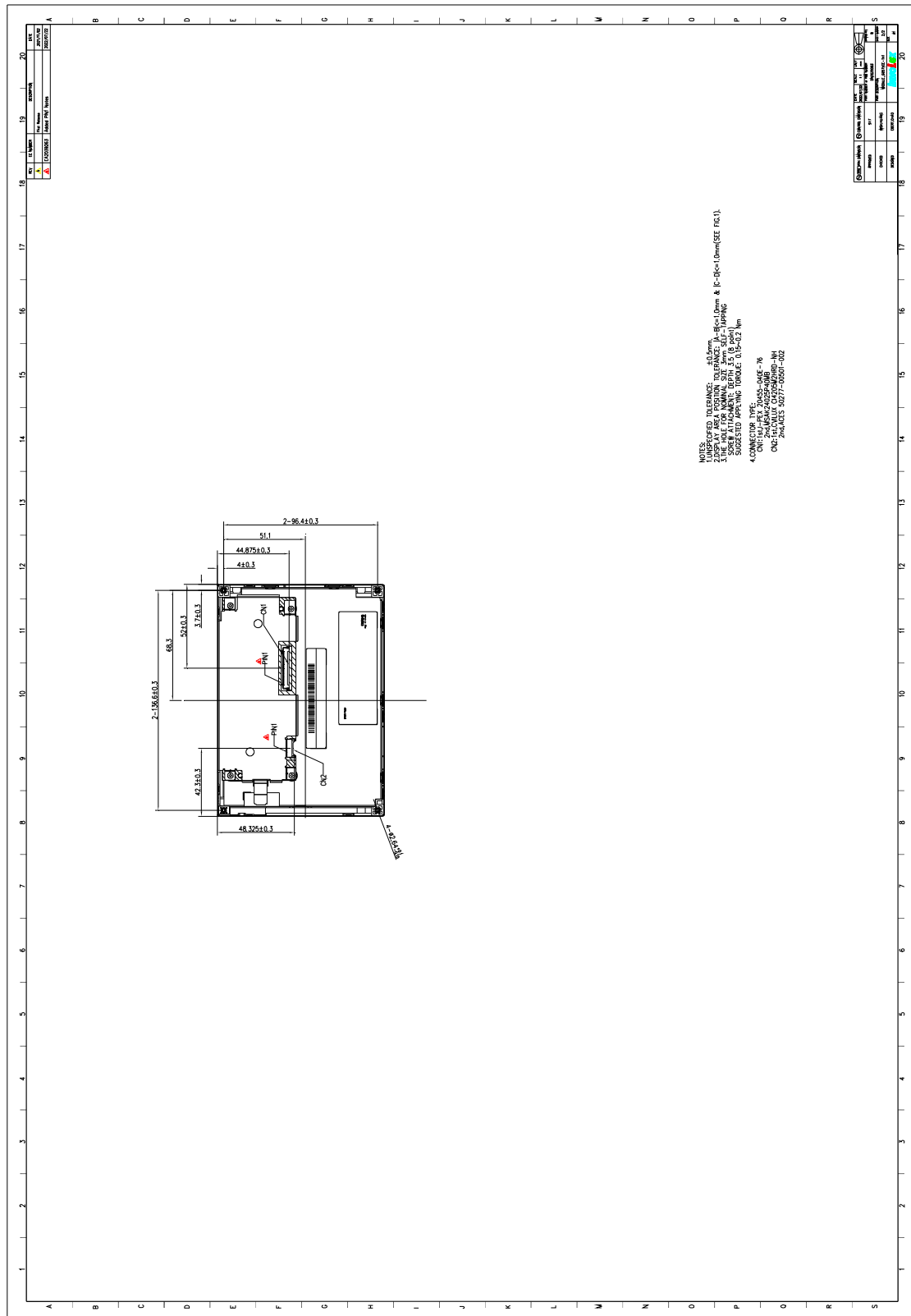
(a) Static information display recommended to use with moving image.

(3) Abnormal condition just means conditions except normal condition.

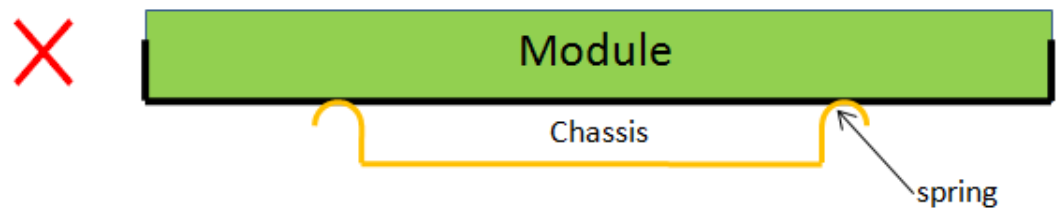
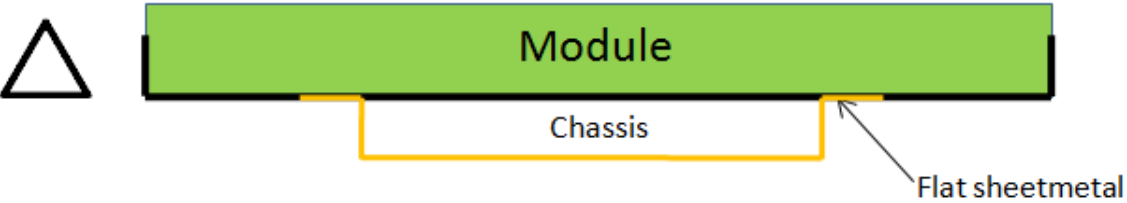
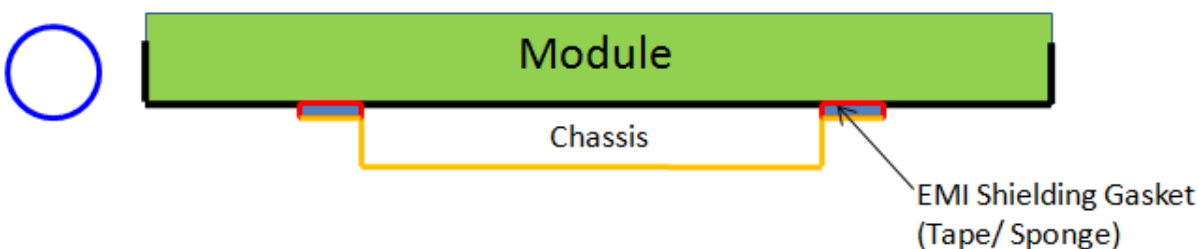


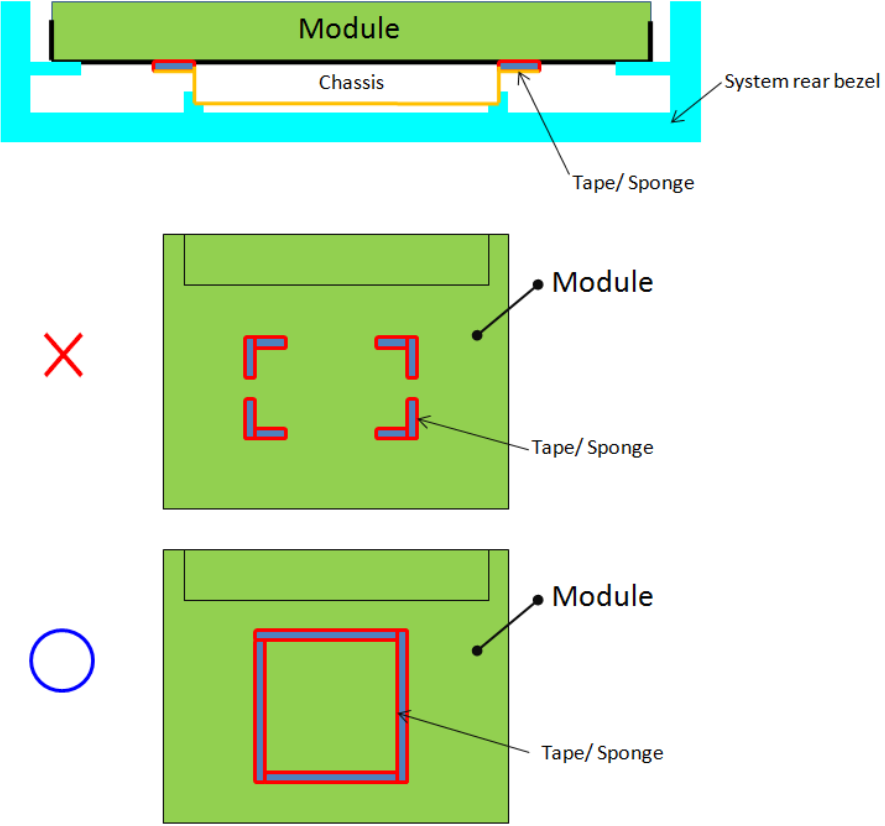
## 12. MECHANICAL CHARACTERISTICS



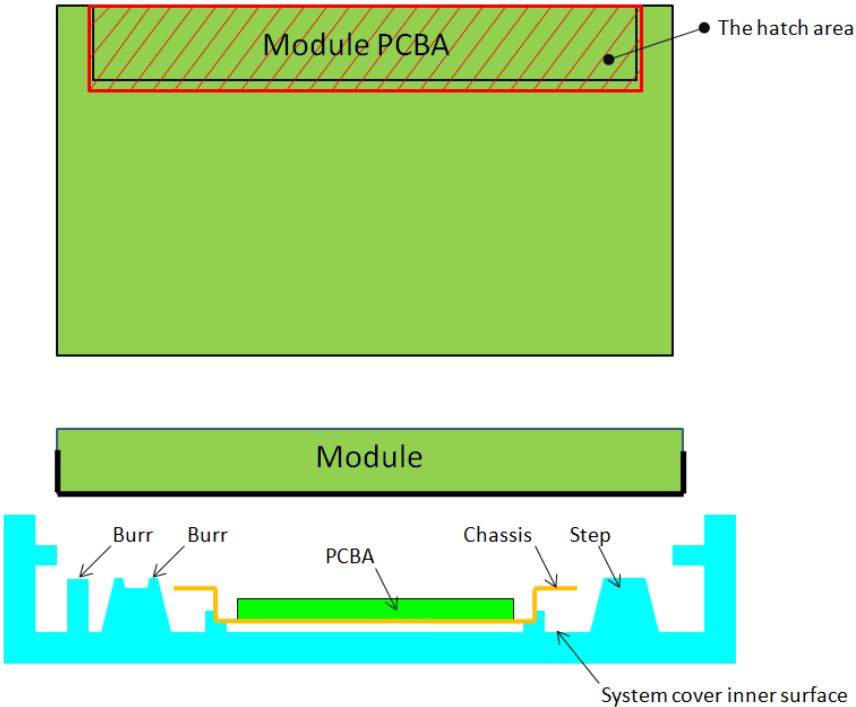


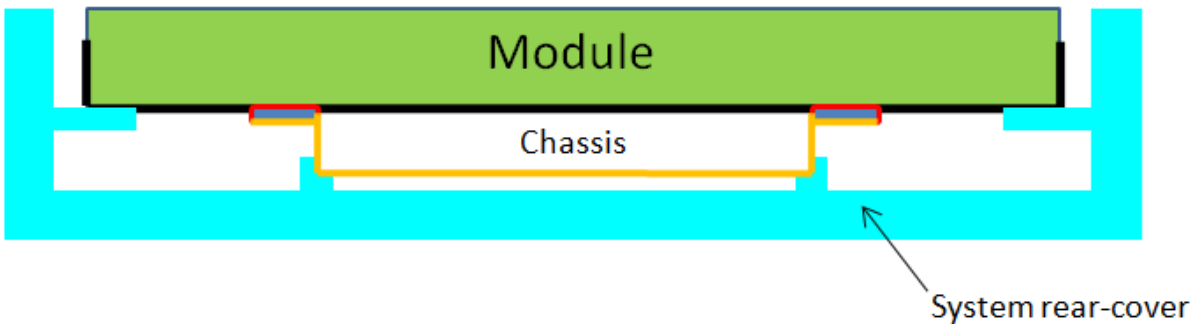
## Appendix. SYSTEM COVER DESIGN NOTICE

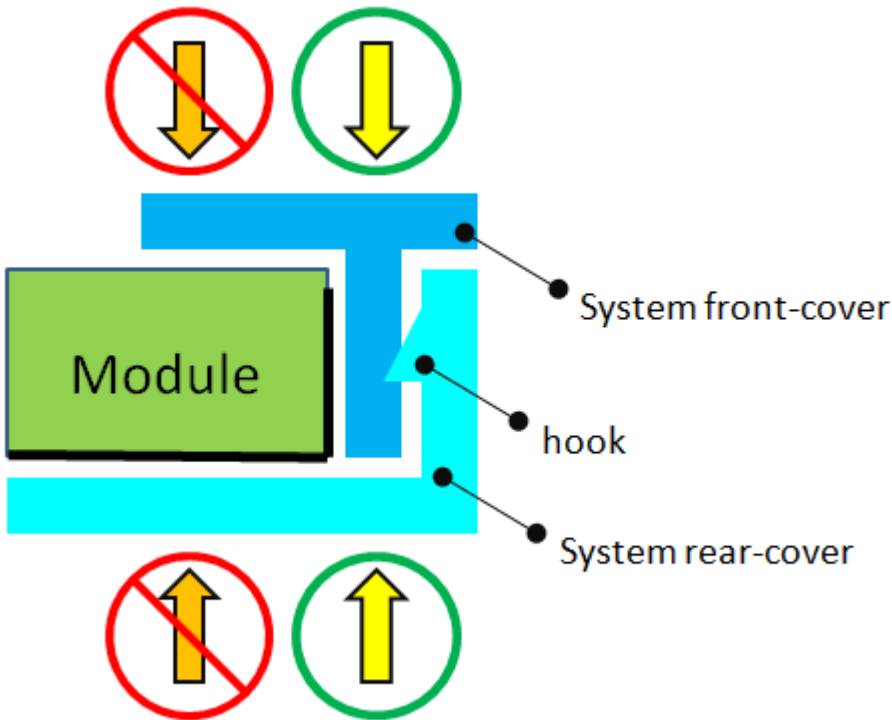
1	Set Chassis and IAVM Module touching Mode
	
	
	
Definition	<p>a. To prevent from abnormal display &amp; white spot after mechanical test, it is not recommended to use spring type chassis.</p> <p>b. We suggest the contact mode between Chassis and Module rear cover is Tape/Sponge, second is Flat sheet metal type chassis.</p>

2	Tape/Sponge design on system inner surface
 <p>The diagram illustrates the correct and incorrect methods for applying Tape/Sponge to the system inner surface. The top part shows a cross-section of a Module (green) mounted on a Chassis (orange) with a System rear bezel (cyan). Tape/Sponge (red) is applied as a continuous strip between the Module and the Chassis. The middle part, marked with a red 'X', shows the Module with four separate L-shaped pieces of Tape/Sponge at the corners. The bottom part, marked with a blue circle, shows the Module with a single rectangular piece of Tape/Sponge covering the entire rear surface.</p>	

Definition	<p>a. To prevent from abnormal display &amp; white spot after mechanical test, we suggest using Tape/Sponge as medium between chassis and Module rear cover could reduce the occurrence of white spot.</p> <p>b. When using the Tape/Sponge, we suggest it be lay over between set chassis and Module rear cover. It is not recommended to add Tape/Sponge in separate location. Since each Tape/Sponge may act as pressure concentration location.</p>
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3	<b>System inner surface examination</b>
	
Definition	<p>a. The hatch area on Module PCBA should keep at least 1mm gap(X,Y,Z direction) to any structure with system cover inner surface.</p> <p>b. Burr, Step, PCB protrusion may cause stress concentration. White spot may occur during reliability test.</p>

4	<b>Material used for system rear-cover</b>
	
Definition	<p>System rear-cover material with high rigidity is needed to resist deformation during scuffing test, hinge test, pogo test or backpack test. Abnormal display, white spot, pooling issue may occur if low rigidity material is used. Pooling issue may occur because screw's boss position for module's bracket are deformed open-close test. Solid structure design of system rear-cover may also influence the rigidity of system rear-cover. The deformation of system rear-cover should not caused interference.</p>

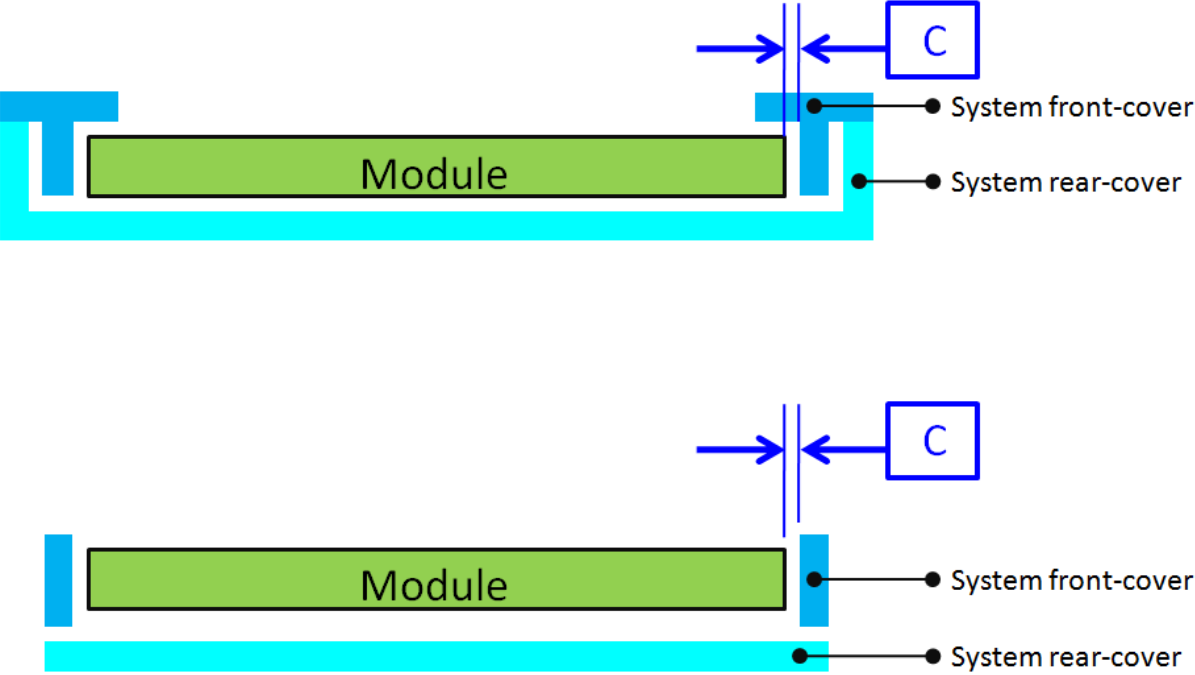
5	<b>Assembly SOP examination for system front-cover with hook structure</b>
	
Definition	<p>To prevent panel crack during system front-cover assembly process with hook structure, it is not recommended to press panel or any location that relate directly to the panel.</p>

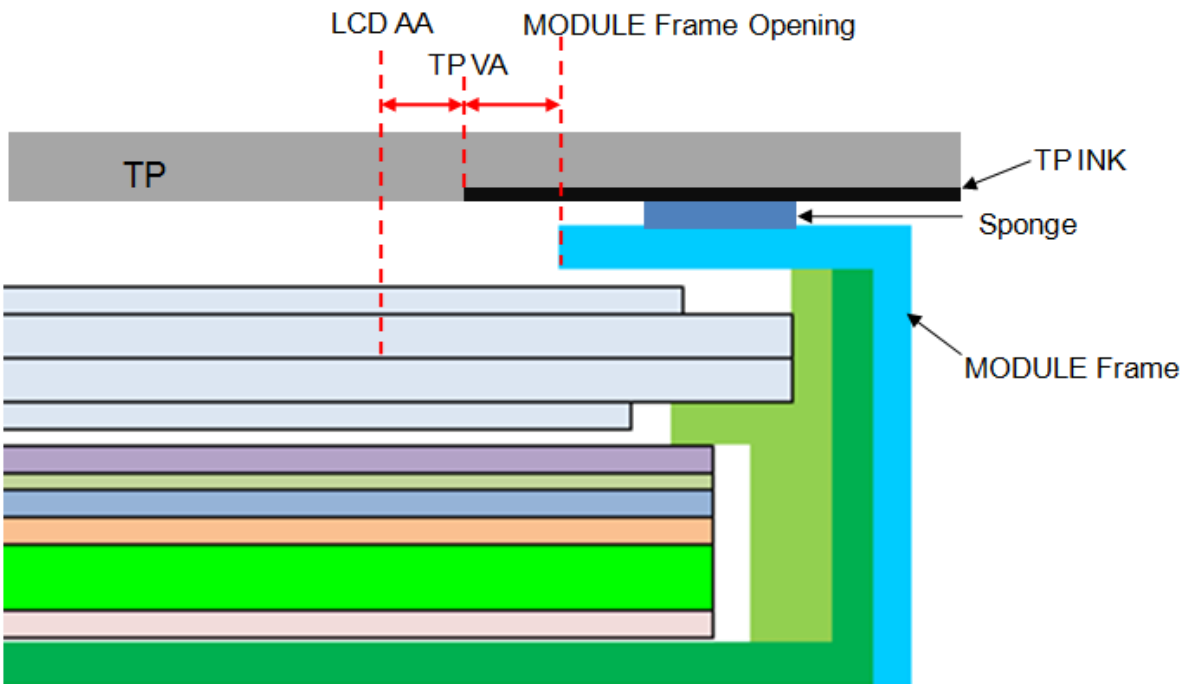
6	Permanent deformation of system cover after reliability test
<p>○</p> <p>×</p> <p>○</p> <p>×</p> <p>×</p> <p>×</p>	<p>System front-cover</p> <p>System rear-cover</p> <p>Module</p> <p>deformation</p> <p>0 gap</p> <p>deformation</p>
Definition	<p>System cover including front cover and rear cover may deform during reliability test. Permanent deformation of system front cover and rear cover after reliability test should not interfere with panel. Because it may cause issue such as pooling, abnormal display, white spot and also cell crack.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>

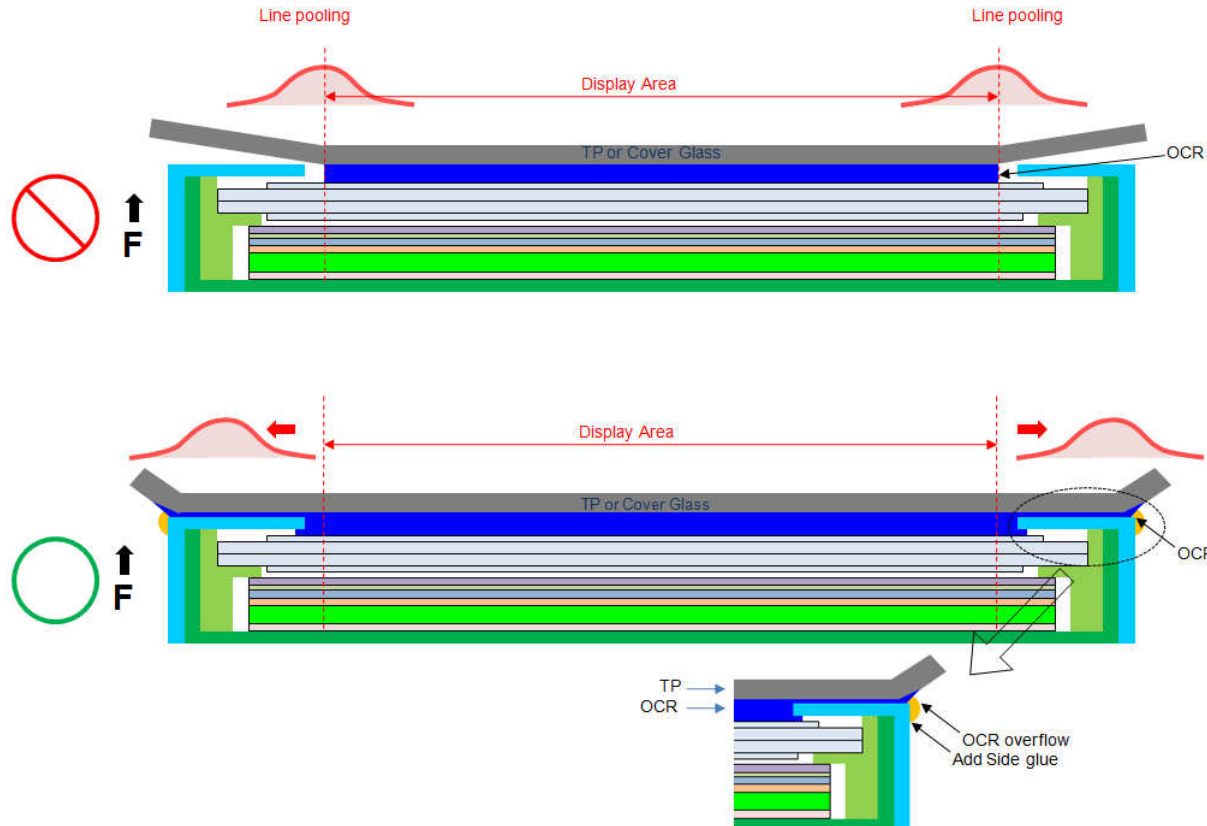
7	<b>Design gap A between panel &amp; any components on system rear-cover</b>
Definition	<p>System cover including front cover and rear cover may deform during reliability test. Permanent deformation of system front cover and rear cover after reliability test should not interfere with panel. Because it may cause issue such as pooling, abnormal display, white spot and also cell creak.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>

8	<b>Design gap B between system front-cover &amp; panel surface</b>
Definition	<p>Gap between system front-cover &amp; panel surface is needed to prevent pooling or glass broken. Zero gap or interference such as burr and warpage from mold frame may cause pooling issue near system front-cover opening edge. This phenomenon is obvious during swing test, hinge test, knock test or during pooling inspection procedure. To remain sufficient gap, design with system rib higher than maximum panel thickness is recommended.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>



9	Design gap C between panel & system front-cover or protrusions
	
Definition	<p>Gap between panel &amp; system front-cover or protrusions is needed to prevent shock test failure. Because system front-cover or protrusions with small gap may hit panel during the test. Issue such as cell crack, abnormal display may occur.</p> <p>The gap should be large enough to absorb the maximum displacement during the test.</p> <p>Note: If the interference cannot be avoided, please feel free to contract INX FAE Engineer for collaboration design. We can help to verify and pass risk assessment for customer reference.</p>

10	Design distance between TP AA to LCD AA
 <p>The diagram illustrates the cross-sectional design of a display module. It shows the TP (Touch Panel) layer, TP INK, a layer of Sponge, and the MODULE Frame. A red double-headed arrow labeled 'TP VA' indicates the design distance between the LCD AA (Active Area) and the MODULE Frame Opening. The LCD AA is represented by a grey layer, and the MODULE Frame Opening is marked by a red dashed line. The TP layer is shown as a grey layer, and the TP INK is shown as a black layer. The Sponge is shown as a blue layer, and the MODULE Frame is shown as a green layer.</p>	
Definition	TP VA should avoid TP ink area covering LCD AA or causing the module frame to be exposed.

11	Use OCR Lamination
	 <p>The diagram illustrates the correct use of OCR lamination to avoid line pooling. It shows two cross-sectional views of a display assembly. The top view, marked with a red 'X' and an upward arrow 'F', shows 'Line pooling' occurring at the edges of the 'Display Area' between the 'TP or Cover Glass' and the underlying layers. The bottom view, marked with a green circle and an upward arrow 'F', shows the same assembly but with 'OCR overflow' and 'Add Side glue' indicated, which prevents line pooling. A detailed inset shows the 'TP' and 'OCR' layers with 'OCR overflow' and 'Add Side glue' indicated by arrows.</p>
Definition	<p>1. OCR glue as possible beyond module, in order to avoid Line Pooling</p> <p>2. Add side glue to avoid Line Pooling</p>